



A Product Line of Diodes Incorporated

ZXTP2041F

### 40V PNP MEDIUM POWER TRANSISTOR IN SOT23

## Features

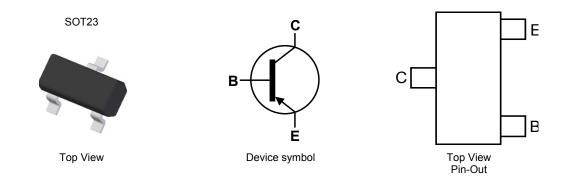
- BV<sub>CEO</sub> > -40V
- I<sub>C</sub> = -1A High Continuous Current
- I<sub>CM</sub> = -2A Peak Pulse Current
- Low Saturation Voltage V<sub>CE(sat)</sub> < -500mV @ -1A</li>
- R<sub>SAT</sub> = 350mΩ for a Low Equivalent On-resistance
- Complementary NPN type: ZXTN2040F
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208<sup>(3)</sup>
- Weight: 0.008 grams (approximate)

## Application

- Power MOSFET gate driving
- Low loss power switching



## Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP2041FTA	P41	7	8	3,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

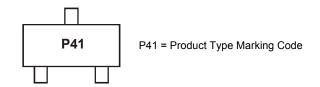
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

# **Marking Information**

Notes:







## **ZXTP2041F**

## Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-40	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-40	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	Ic	-1	A
Peak Pulse Current	I <sub>CM</sub>	-2	A
Base Current	I <sub>B</sub>	-200	mA
Peak Base Current	I <sub>BM</sub>	-1	A

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 5)	Р	310	mW	
	(Note 6)	- P <sub>D</sub>	350	11100	
Thermal Desistance Junction to Ambient	(Note 5)	D	403	0000	
Thermal Resistance, Junction to Ambient	(Note 6)	R <sub>0JA</sub>	357	°C/W	
Thermal Resistance, Junction to Leads (Note 7)		R <sub>θJL</sub>	350	°C/W	
Operating and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 to +150	°C		

### ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes: 5. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

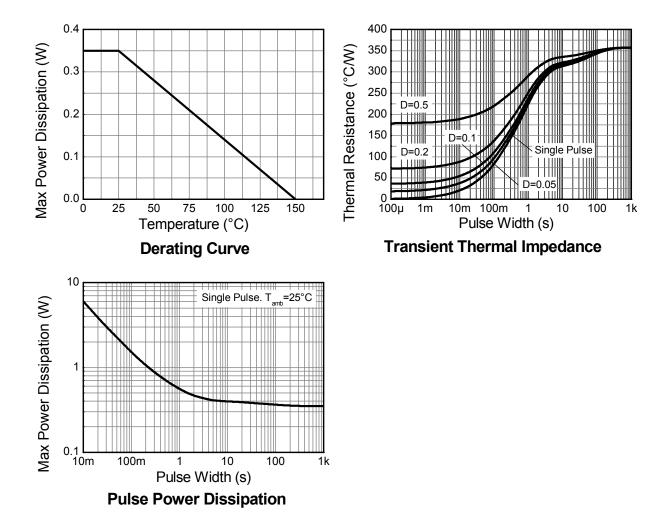
6. Same as note (5), except the device is mounted on 15 mm x 15mm 1oz copper.

Thermal resistance from junction to solder-point (at the end of the leads).
 Refer to JEDEC specification JESD22-A114 and JESD22-A115.





# Thermal Characteristics and Derating Information







ZXTP2041F

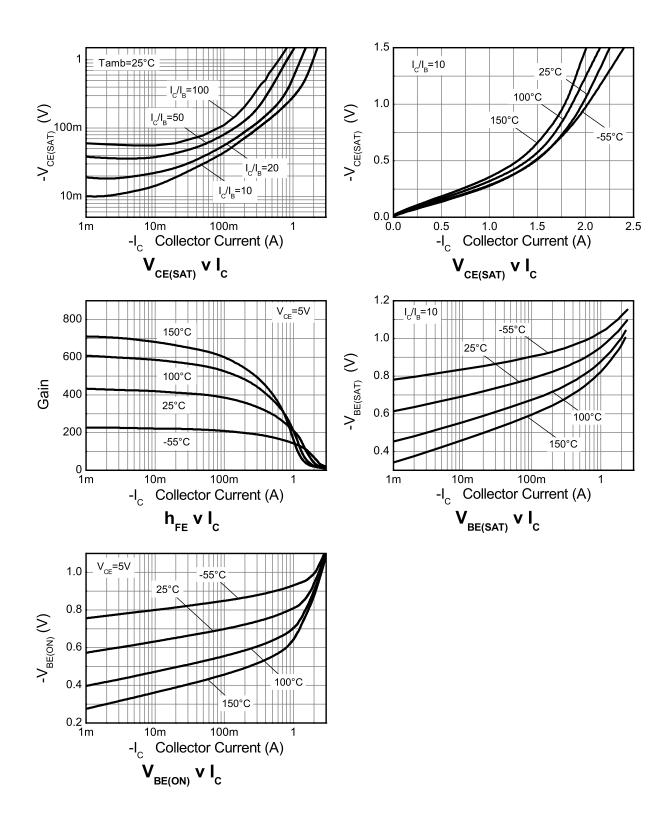
Electrical C	haracteristics (@T <sub>A</sub> =	+25°C, unless oth	erwise spec	cified.)			
	Characteristic	Symbol	Min	Тур.	Max	Unit	Test Condition
Collector-Base Breakdown Voltage		BV <sub>CBO</sub>	-40	-	-	V	I <sub>C</sub> = -100μA
Collector-Emitter	Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	-40	-	-	V	I <sub>C</sub> = -10mA
Emitter-Base Bre	akdown Voltage	BV <sub>EBO</sub>	-7	-	-	V	I <sub>E</sub> = -100μA
Collector Cutoff C	Current	I <sub>CBO</sub>	-	-	-100	nA	V <sub>CB</sub> = -30V
Emitter Cutoff Cu	rrent	I <sub>EBO</sub>	-	-	-100	nA	V <sub>EB</sub> = -5.6V
Emitter Cutoff Cu	rrent	ICES	-	-	-100	nA	$V_{CE} = -30V$
			300	-	-	-	I <sub>C</sub> = -1mA, V <sub>CE</sub> = -5V
		h <sub>FE</sub>	300	-	800		I <sub>C</sub> = -100mA, V <sub>CE</sub> = -5V
DC current transf	er Static ratio (Note 9)		250	-	-		I <sub>C</sub> = -500mA, V <sub>CE</sub> = -5V
			160	-	-		I <sub>C</sub> = -1A, V <sub>CE</sub> = -5V
			30	-	-		I <sub>C</sub> = -2A, V <sub>CE</sub> = -5V
		V <sub>CE(sat)</sub>	-	-	-200	mV	I <sub>C</sub> = -100mA, I <sub>B</sub> = -1mA
Collector-Emitter	Saturation Voltage (Note 9)		-	-	-350		I <sub>C</sub> = -500mA, I <sub>B</sub> = -20mA
		. ,	-	-	-500		I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
Base-Emitter Saturation Voltage (Note 9)		V <sub>BE(sat)</sub>	-	-	-1.1	V	I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
Base-Emitter Tur	n-on Voltage (Note 9)	V <sub>BE(on)</sub>	-	-	-1.0	V	I <sub>C</sub> = -1A, V <sub>CE</sub> = -5V
Transitional Frequency		f <sub>T</sub>	150	300	-	MHz	I <sub>C</sub> = -50mA, V <sub>CE</sub> = -10V, f = 100MHz
Output capacitance		C <sub>obo</sub>	-	-	10	pF	V <sub>CB</sub> = -10V, f = 1MHz,
	Delay Time	t <sub>(d)</sub>	-	34.9	-		
Switching Time	Rise Time	t <sub>(r)</sub>	-	19.2	-		V <sub>CC</sub> = -10V, I <sub>C</sub> = -500mA,
Switching Time	Storage Time	t <sub>(s)</sub>	-	249	-	ns	$I_{B1} = -I_{B2} = -25mA$
	Fall Time	t <sub>(f)</sub>	-	62	-	1	

9. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$ 2%. Notes:



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# Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

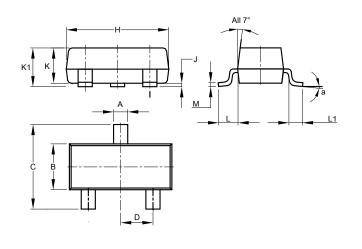






## **Package Outline Dimensions**

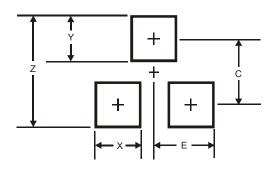
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
К	0.890	1.00	0.975		
K1	0.903	1.10	1.025		
L	0.45	0.61	0.55		
L1	0.25	0.55	0.40		
М	0.085	0.150	0.110		
а	8°				
All	All Dimensions in mm				

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
Z	2.9		
Х	0.8		
Y	0.9		
С	2.0		
E	1.35		





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